

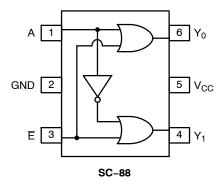
1-to-2 Decoder/ Demultiplexer

NLV7SZ19

The NLV7SZ19 is a 1–to–2 decoder. When the output enable (\overline{E}) is Low, the device passes data at input A to outputs Y0 (true) and Y1 (complement). The NL7SZ19 can also be used as a 1–to–2 demultiplexer. As a demultiplexer, data at input E is routed to either Y0 or Y1 depending on the state of A. The device operates over the voltage range from 1.65 V to 5.5 V.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- 2.7 ns t_{PD} at $V_{CC} = 5 \text{ V (Typ)}$
- Inputs/Outputs Overvoltage Tolerant up to 5.5 V
- I_{OFF} Supports Partial Power Down Protection
- Sink 32 mA at 5.0 V
- Available in SC-88 and UDFN6 Packages
- Chip Complexity < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



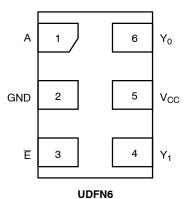


Figure 1. Pinout (Top View)





SC-88 DF SUFFIX CASE 419B UDFN6, 1.2x1.0, 0.4P CASE 517AA-01

MARKING DIAGRAMS





X, XXX = Specific Device Code
M = Date Code*
= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

PIN ASSIGNMENT

Pin	Function
1	A
2	GND
3	Ē
4	Y ₁
5	V _{CC}
6	Y ₀

FUNCTION TABLE

Ē	Α	$Y_0 = A + \overline{E}$	$Y_1 = \overline{A} + \overline{E}$
L	L	L	Н
L	Н	Н	L
Н	Н	Н	Н
Н	L	Н	Н

MAXIMUM RATINGS

Symbol	Characteristics		Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
V _{IN}	DC Input Voltage		-0.5 to +7.0	V
V _{OUT}	DC Output Voltage (NLV) Active-Mode (High or I Tri-State Mod Power-Down Mode (\)	de (Note 1)	-0.5 to V _{CC} + 0.5 -0.5 to +7.0 -0.5 to +7.0	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
I _{OK}	DC Output Diode Current V _O	out < GND	-50	mA
I _{OUT}	DC Output Source/Sink Current		±50	mA
I _{CC} or I _{GND}	DC Supply Current per Supply Pin or Ground Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 secs		260	°C
TJ	Junction Temperature Under Bias		+150	°C
$\theta_{\sf JA}$	Thermal Resistance (Note 2)	SC-88 UDFN6	377 154	°C/W
P _D	Power Dissipation in Still Air	SC-88 UDFN6	332 812	mW
MSL	Moisture Sensitivity		Level 1	-
F _R	Flammability Rating Oxygen Index	x: 28 to 34	UL 94 V-0 @ 0.125 in	-
V _{ESD}	ESD Withstand Voltage (Note 3) Human Book Charged Dev	ody Model vice Model	2000 1000	٧
I _{Latchup}	Latchup Performance (Note 4)		± 100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri–stated.

- Applicable to devices with outputs that may be the stated.
 Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.
 HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.
 Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics			Max	Unit
V _{CC}	Positive DC Supply Voltage		1.65	5.5	V
V _{IN}	DC Input Voltage		0	5.5	V
V _{OUT}	DC Output Voltage	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	0 0 0	V _{CC} 5.5 5.5	
T _A	Operating Temperature Range		-55	+125	°C
t _r , t _f	Input Rise and Fall Time	$\begin{array}{c} V_{CC} = 1.65 \ V \ to \ 1.95 \ V \\ V_{CC} = 2.3 \ V \ to \ 2.7 \ V \\ V_{CC} = 3.0 \ V \ to \ 3.6 \ V \\ V_{CC} = 4.5 \ V \ to \ 5.5 \ V \end{array}$	0 0 0 0	20 20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	T	A = 25°	С	–55°C ≤ T	_A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
V _{IH}	High-Level Input	=	1.65 to 1.95	0.75 x V _{CC}	-	_	0.75 x V _{CC}	-	V
	Voltage		2.3 to 5.5	0.70 x V _{CC}	-	_	0.70 x V _{CC}	-	
V _{IL}	Low-Level Input	-	1.65 to 1.95	-	-	0.25 x V _{CC}	-	0.25 x V _{CC}	V
	Voltage		2.3 to 5.5	-	-	0.30 x V _{CC}	-	0.30 x V _{CC}	
V _{OH}	High-Level Output Voltage	$\begin{array}{l} V_{IN} = V_{IH} \text{ or } V_{IL} \\ I_{OH} = -100 \mu\text{A} \\ I_{OH} = -4 \text{ mA} \\ I_{OH} = -8 \text{ mA} \\ I_{OH} = -16 \text{ mA} \\ I_{OH} = -24 \text{ mA} \\ I_{OH} = -32 \text{ mA} \end{array}$	1.65 to 5.5 1.65 2.3 3 3 4.5	V _{CC} - 0.1 1.29 1.9 2.4 2.3 3.8	V _{CC} 1.52 2.1 2.7 2.5 4	- - - -	V _{CC} - 0.1 1.29 1.9 2.4 2.3 3.8	- - - -	V
V _{OL}	Low-Level Output Voltage	$\begin{array}{l} V_{IN} = V_{IH} \text{ or } V_{IL} \\ I_{OH} = 100 \mu\text{A} \\ I_{OH} = 4 \text{ mA} \\ I_{OH} = 8 \text{ mA} \\ I_{OH} = 16 \text{ mA} \\ I_{OH} = 24 \text{ mA} \\ I_{OH} = 32 \text{ mA} \end{array}$	1.65 to 5.5 1.65 2.3 3 3 4.5	- - - - -	- 0.08 0.12 0.24 0.26 0.31	0.1 0.24 0.3 0.4 0.55 0.55	- - - - -	0.1 0.24 0.3 0.4 0.55 0.55	>
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	1.65 to 5.5	-	_	±0.1	-	±1.0	μΑ
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0	-	-	1.0	-	10	μΑ
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND	5.5	-	-	1.0	-	10	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

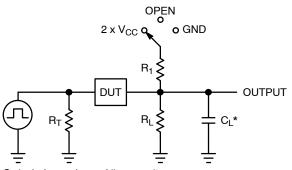
AC ELECTRICAL CHARACTERISTICS

			V _{CC}	T _A = 25°C			-55°C ≤ T _A ≤ 125°C		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
t _{PLH} ,	. ,	$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	1.65 to 1.95	_	6.2	10.5	-	11.0	ns
t _{PHL}	(Figures 2 and 3)	$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	2.3 to 2.7	_	3.6	6.0	-	6.4	
		$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	3.0 to 3.6	_	2.9	4.1	-	4.5	
		R_L = 500 Ω, C_L = 50 pF		_	3.2	5.1	=	5.4	
		$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	4.5 to 5.5	_	2.4	3.2	=	3.5	
		R_L = 500 Ω, C_L = 50 pF		_	2.7	4.0	-	4.3	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC}	2.5	pF
C _{OUT}	Output Capacitance	V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC}	2.5	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	10 MHz, V_{CC} = 3.3 V, V_{IN} = 0 V or V_{CC} 10 MHz, V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC}	9 11	pF

^{5.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.



Test	Switch Position	C _L , pF	R_L, Ω	R ₁ , Ω
t _{PLH} / t _{PHL}	Open	See AC Characteristics Table		
t _{PLZ} / t _{PZL}	2 x V _{CC}	50	500	500
t _{PHZ} / t _{PZH}	GND	50	500	500

X = Don't Care

 C_L includes probe and jig capacitance R_T is Z_{OUT} of pulse generator (typically 50 $\Omega)$

f = 1 MHz

Figure 2. Test Circuit

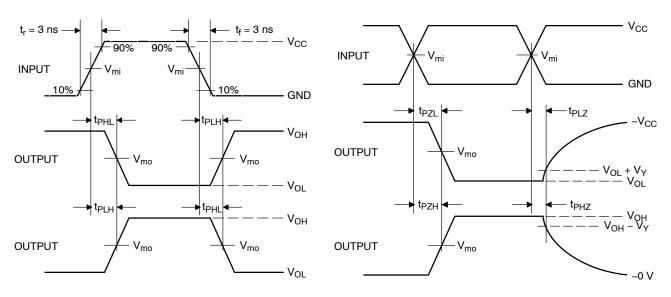


Figure 3. Switching Waveforms

		V _m		
V _{CC} , V	V _{mi} , V	t _{PLH} , t _{PHL}	t _{PZL} , t _{PLZ} , t _{PZH} , t _{PHZ}	V _Y , V
1.65 to 1.95	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.15
2.3 to 2.7	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.15
3.0 to 3.6	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.3
4.5 to 5.5	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.3

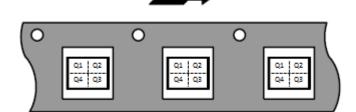
DEVICE ORDERING INFORMATION

Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping [†]
NLV7SZ19DFT2G*	SC-88	LE	Q4	3000 / Tape & Reel
NL7SZ19MUR2G	UDFN6, 1.2 x 1.0, 0.4P	U	Q2	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP

PIN 1 ORIENTATION IN TAPE AND REEL

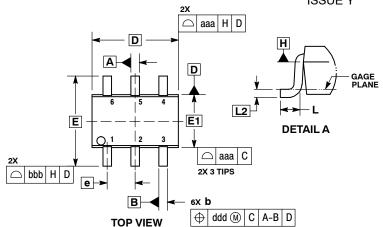
Direction of Feed

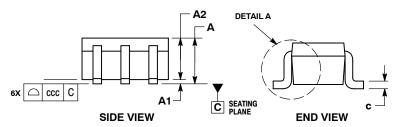


PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363

CASE 419B-02 **ISSUE Y**





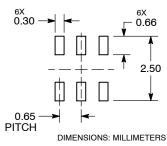
NOTES:

- TES:
 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
 PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
 DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF

- DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H.
 DATUMS A AND B ARE DETERMINED AT DATUM H.
 DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
 DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION.
 ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION b AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

	MIL	LIMETE	ERS		INCHES	3	
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α			1.10			0.043	
A1	0.00		0.10	0.000		0.004	
A2	0.70	0.90	1.00	0.027	0.035	0.039	
b	0.15	0.20	0.25	0.006	0.008	0.010	
С	0.08	0.15	0.22	0.003	0.006	0.009	
D	1.80	2.00	2.20	0.070	0.078	0.086	
E	2.00	2.10	2.20	0.078	0.082	0.086	
E1	1.15	1.25	1.35	0.045	0.049	0.053	
е		0.65 BS	С	0	0.026 BSC		
L	0.26	0.36	0.46	0.010	0.014	0.018	
L2	0.15 BSC 0			0.006 BS	SC		
aaa	0.15				0.006		
bbb	0.30				0.012		
ccc	0.10				0.004		
ddd		0.10			0.004		

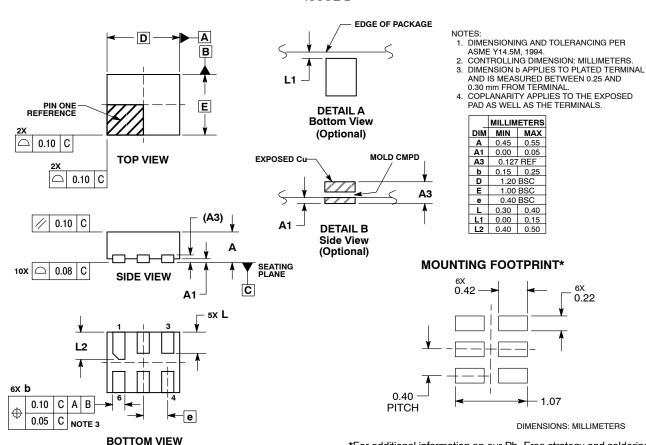
RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

UDFN6, 1.2x1.0, 0.4P CASE 517AA ISSUE D



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